



The PHENIX Multiplicity Vertex Detector

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Physics Goals

Design Criteria

MVDSchematic

Silicon Detector Design

Prototype electronics & Beamtest

Mechanical Progress

Prototyping

Milestones

Physics Goals

- * Charged particle multiplicity
- * $d^2N/d\eta d\phi$
- * Centrality trigger at LVL-1
- * Collision vertex position ($\sigma < 2\text{mm}$)

Design Goals

- * Large rapidity coverage ($\Delta\eta = 5$)
- * Good azimuthal coverage & granularity
- * Minimum material in electron arm acceptance
- * Minimize cost

MVD Collaboration

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Clamshell design - mounts to magnet pole faces
Inner and Outer barrels of silicon strip detectors
200um, 64cm long
Silicon pad endcaps +/- 35cm

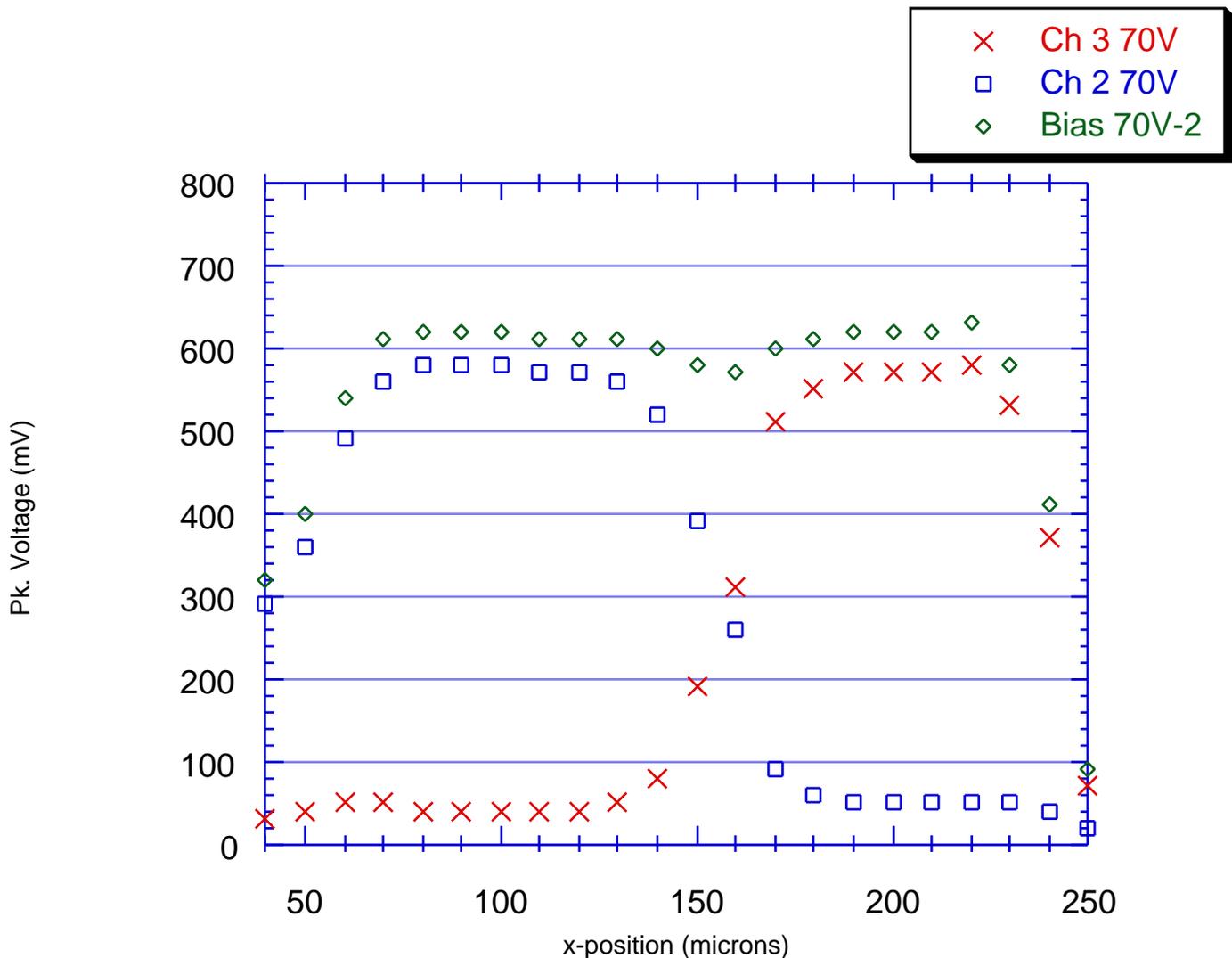
Strip electronics at bottom
256 ch/ Si detector
Channel count = 34,816

"C" shaped detector assemblies
Support Structure - Rohacell foam
50 μ m kapton cables: Si to MCM

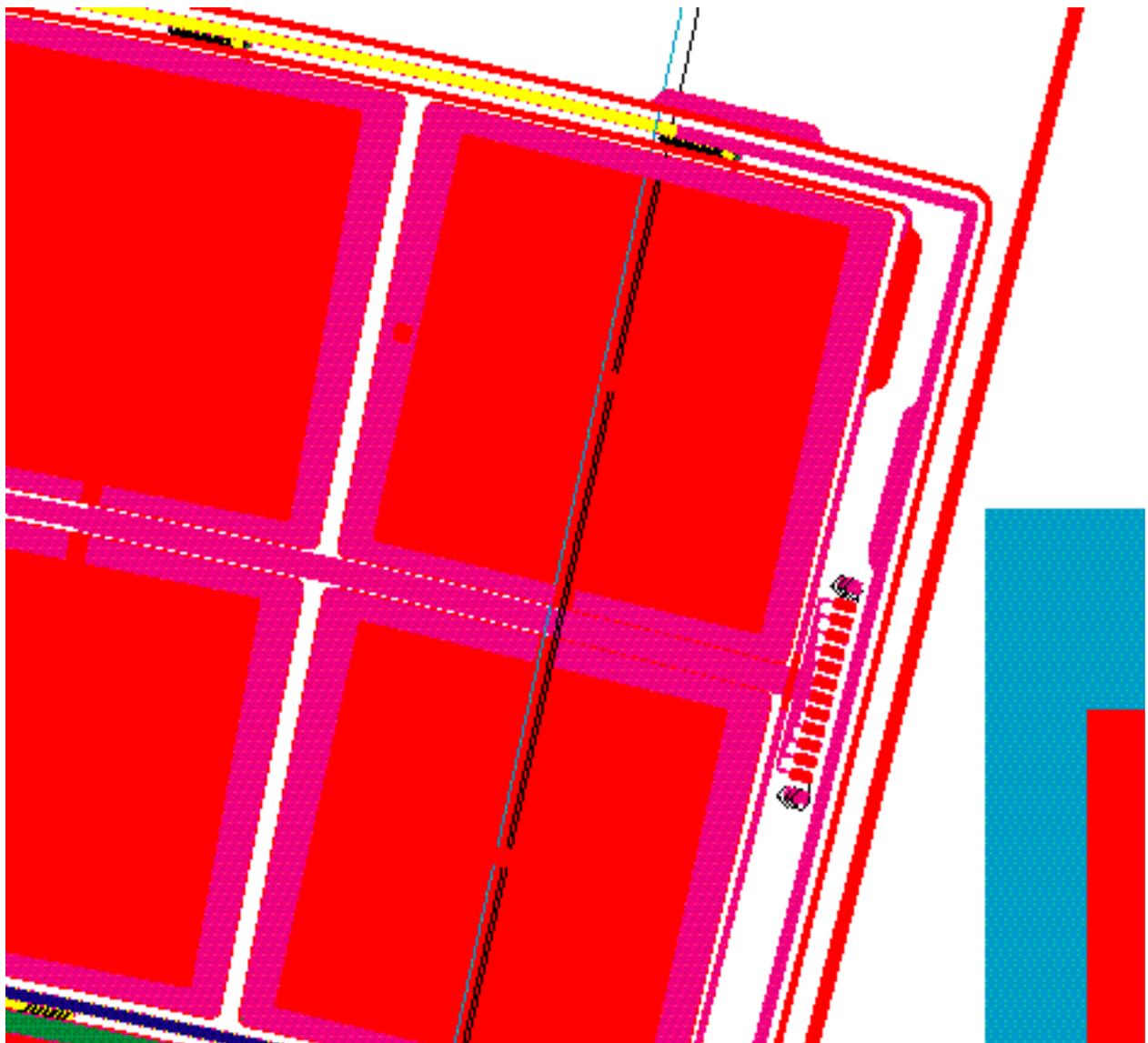
6 MCM per Air-cooling plenum section
Rohacell plenum
Power & Communication Bus exit base of plenum

Silicon Strip Detector

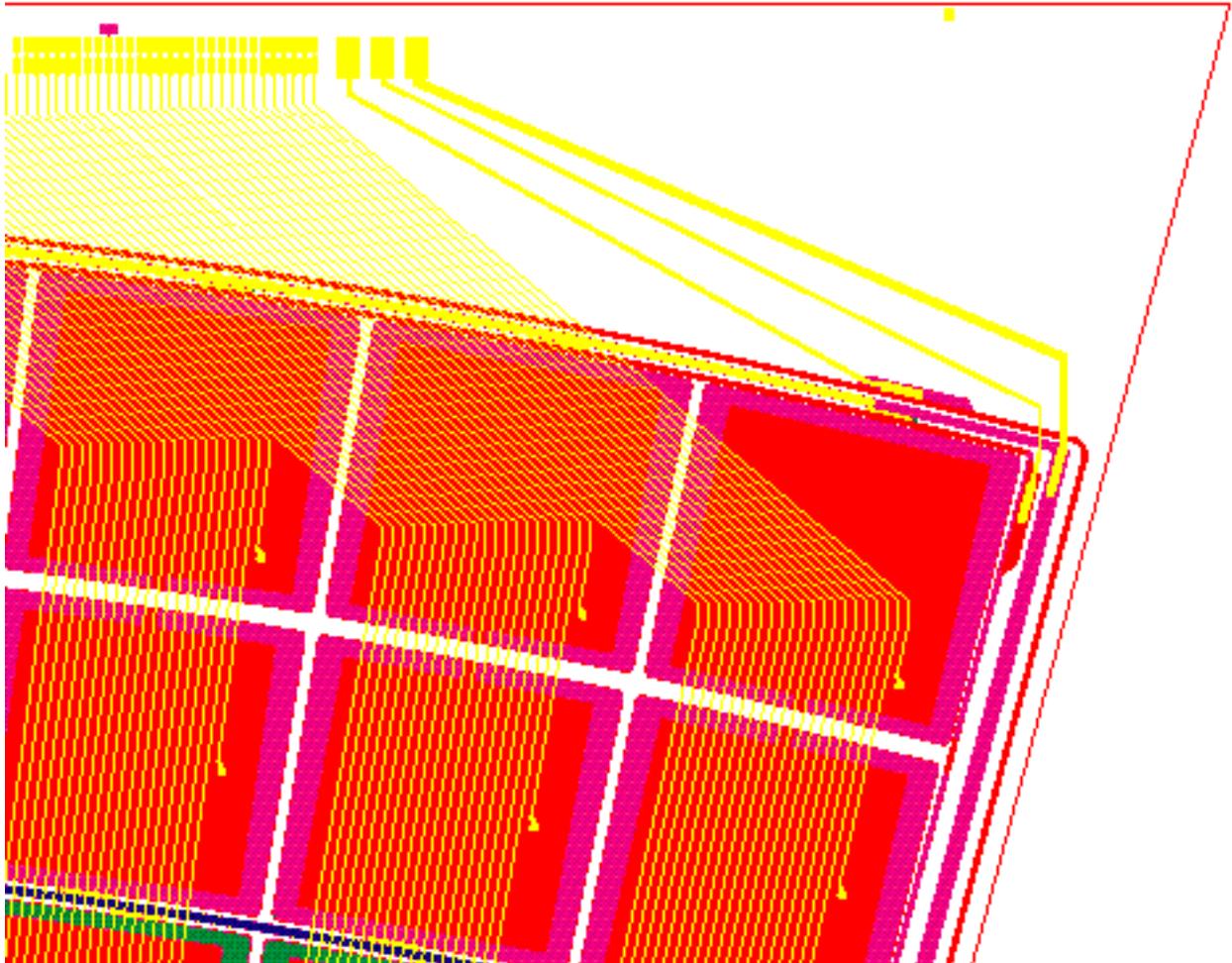
- * Designed & prototyped-MicronSemiconductor
200 μm pitch, 300 μm thick
- * Evaluated in lab- probe, laser station
- * Tested in beam



Single Metal Pad Detector

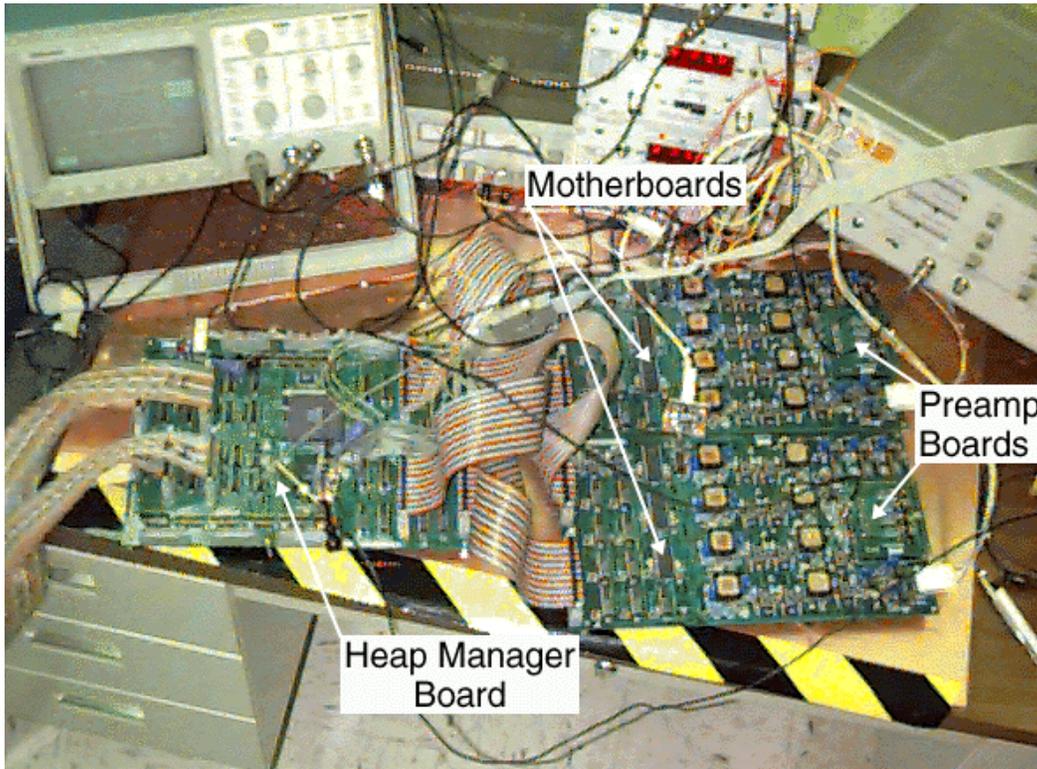


Double Metal Pad Detector



- * Eliminates specialized kapton cable
- * Reduces wirebonding
- * Facilitates detector probing
- * Facilitates assembly, handling
- * Increases yield
- * Sequential readout

Front-end Electronics



Basic components:
8ch preamp, AMU, ADC,
Heap Manager (1/4 Phenix clock)

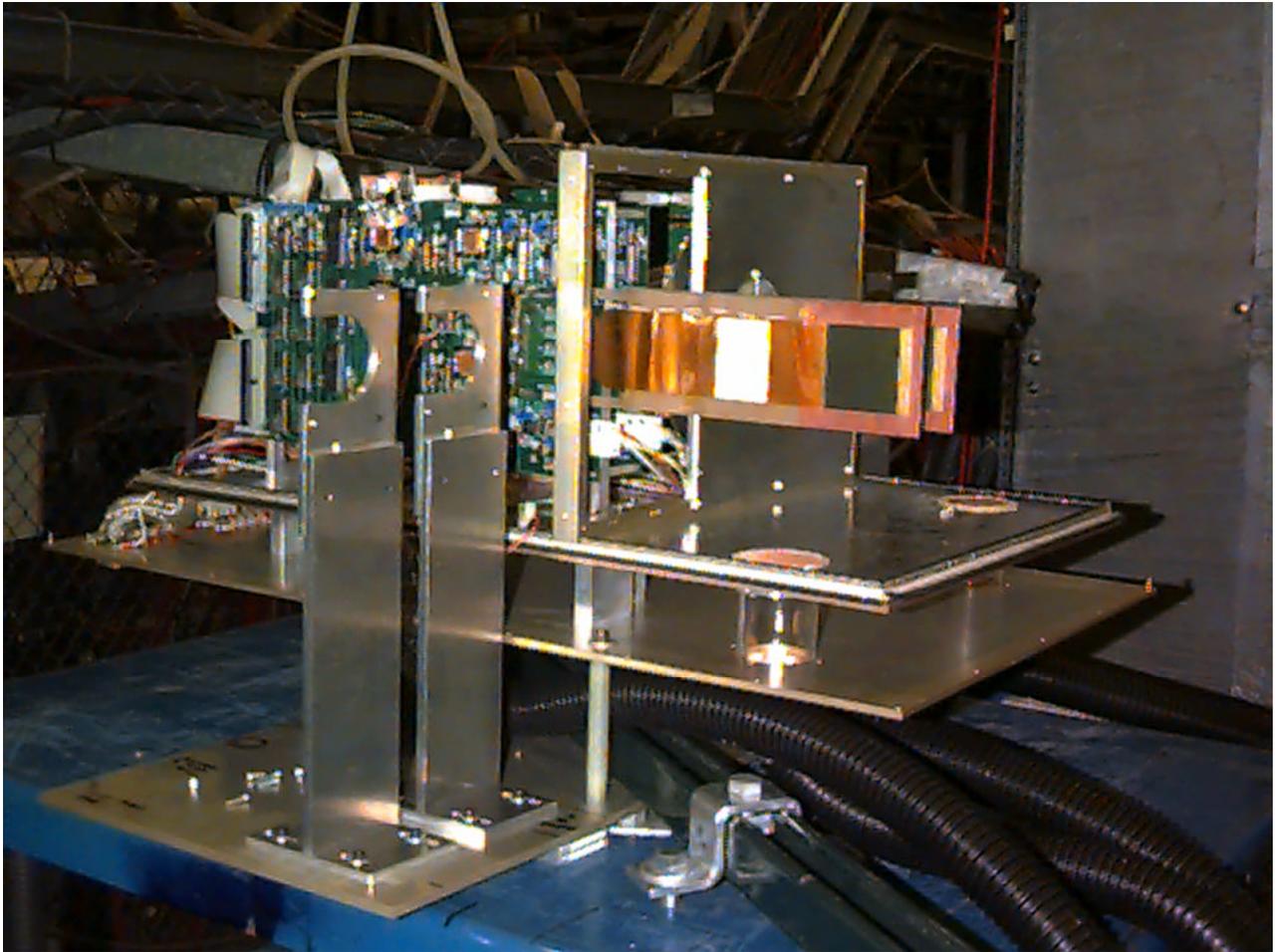
ADC - Nonlinearity of response - worsening
of resolution in low range

3-Board set used in Beam test

MCM Pre-Prototype Development

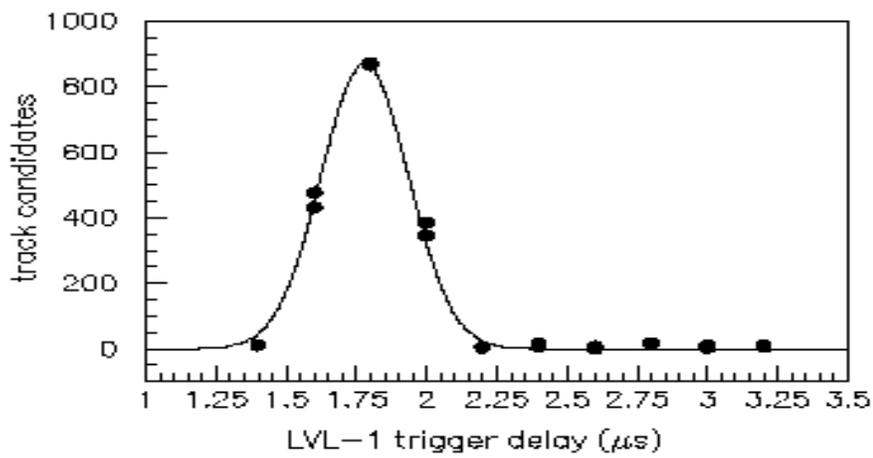
32 channel MCM
8 channel die
Preamp, AMU, ADC, FPGA

AGS Beam Test

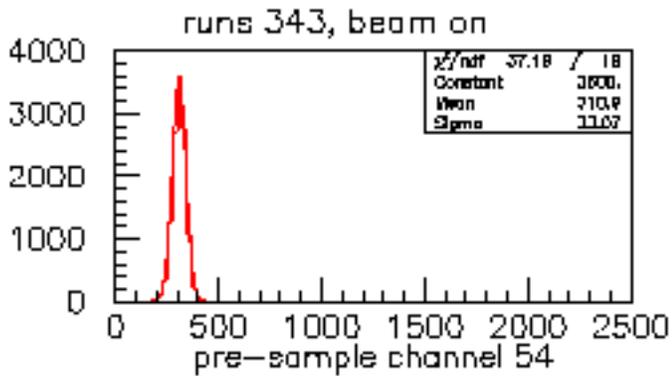


Prototype electronics, DAQ
Prototype Si strip detectors, kapton cables
Prototype RF enclosure

Beam Test Data

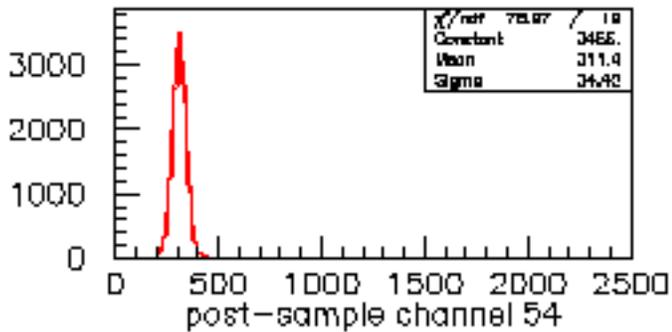


Beam Test Data



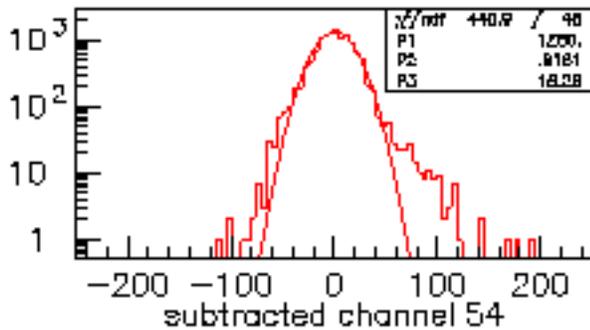
Presample:

ADC values before event
Includes high & low freq noise



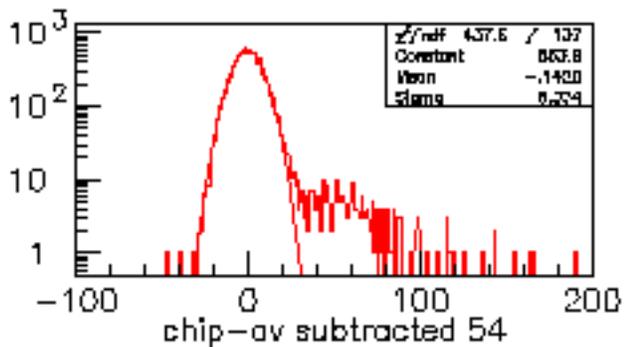
Post-sample:

ADC values after event
Includes high & low freq noise



Post-pre:

Subtract ped and low freq noise
High freq noise remains



<Chip> subtraction:

Removes high freq noise
Remaining width due to ADC resolution

Mechanical Progress

All mechanical components designed
(Pre Mechanical Design Review July 30)

Mounting, Truss, Detector supports, Enclosure,
Cables, Motherboard, Connector ID, Cooling
systems....

Engineering analysis - MCM Cooling, Detector
Support Deflection, Foam Environmental

Truss Structure Deflection studies
Detector Support Deflection studies
Rohacell Cage Environmental
Rohacell Cage Mechanical Stability
Thermal and Electrical Studies of Enclosure
Enclosure formation and assembly procedure
MCM Air Cooling Studies
Air-induced Vibrational Studies
Motherboard water cooling system

Extensive prototyping



MCM Cooling System:

Air Cooling (10°C min)
10mW/chan
2x safety margin

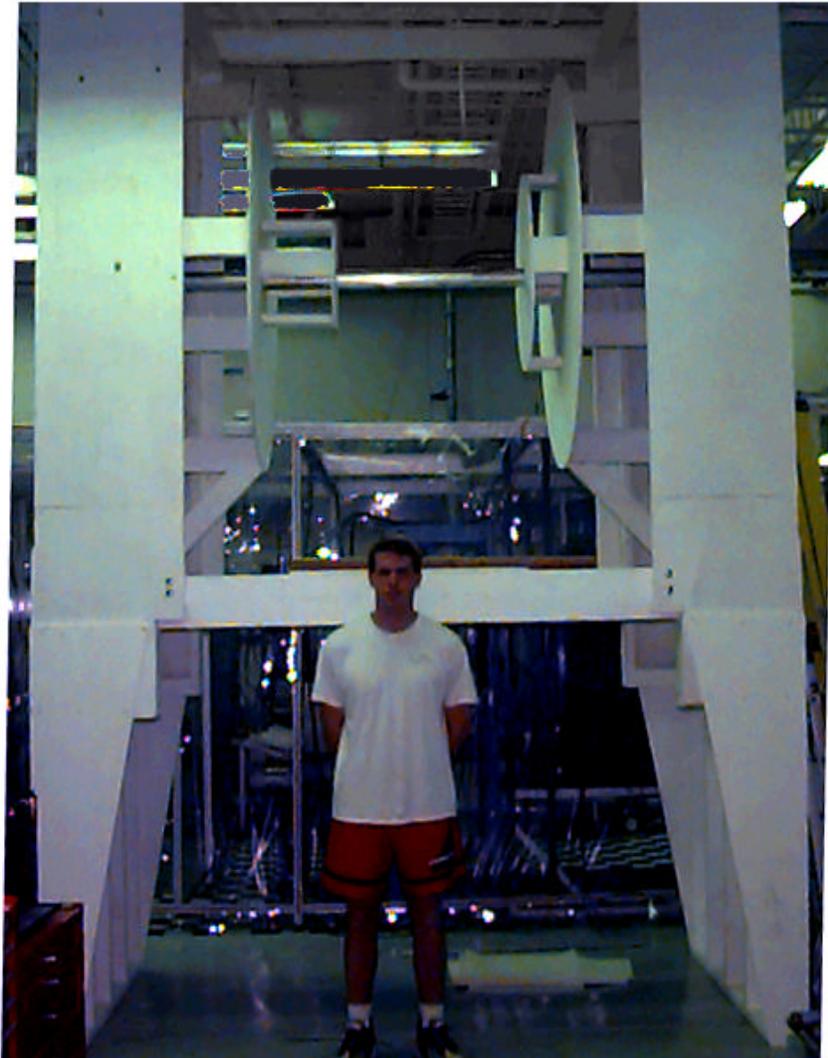
Motherboard Cooling System

Water : $10\text{-}25^{\circ}\text{C}$

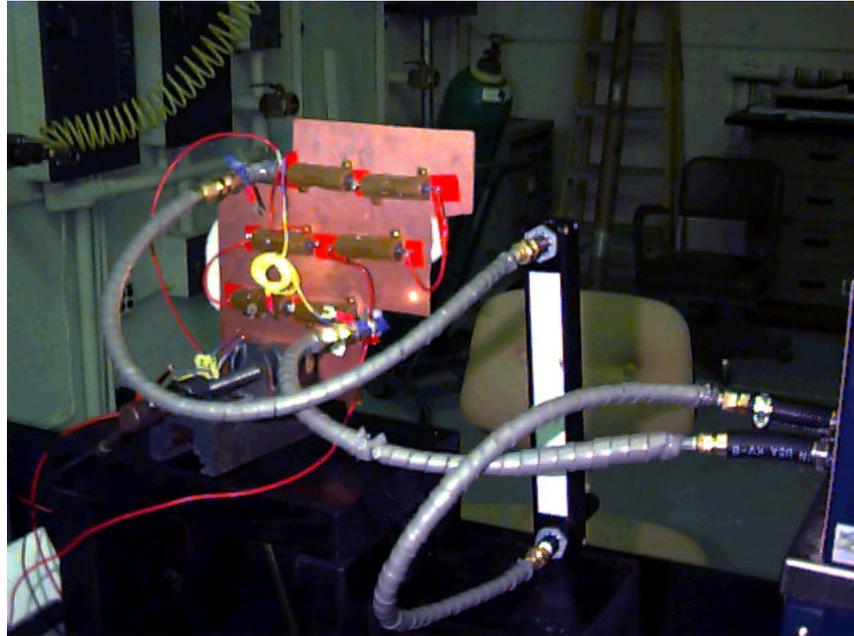
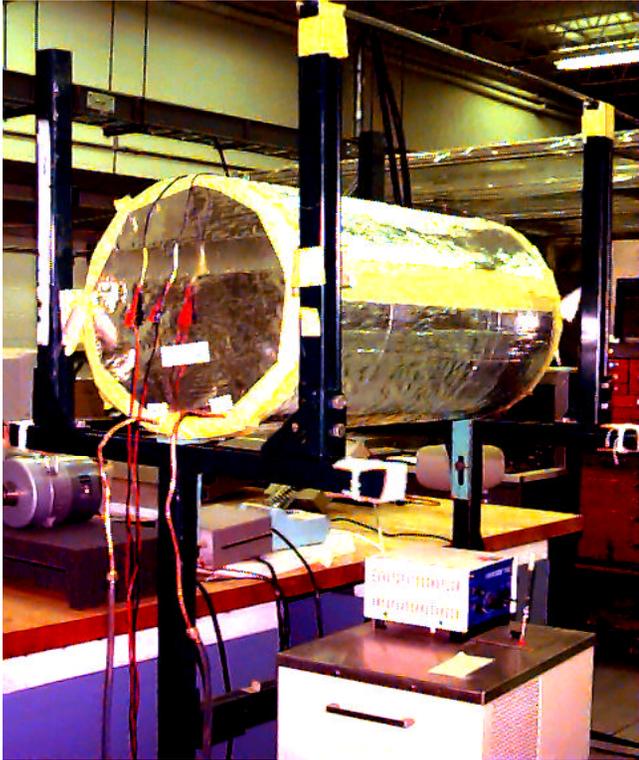
Silicon Detector Cooling System

Air: $10\text{-}25^{\circ}\text{C}$

Prototyping



Fullscale!
Represent all mechanical components
Mechanical studies
Assembly issues, jigs
Cables, connectors
Integration
Assembly procedure



Mechanical:

Vertex detector design complete	Mar-96
Pad detector design complete	May-96
MVD Chain Test	Apr-96
Mechanical design -prelim	Jul-96
Cooling design -prelim	Jul-96
All detectors received	Apr-97
Final Mech design review	Dec-96
Subassemblies complete	Mar-98
Assembly complete	Oct-98

Front-end Electronics:

Review TGV R2	Nov-95
Review AMU/ADC R1	Mar-96
FEE Prelim design review	Aug-96
Review AMU/ADC R2	Oct-96
Review TGV R3	Oct-96
Review Prot MCM w/vendor	Nov-96
MCM Design Complete	Jun-97
Chip Fab Complete	Jun-97
MCMs complete	Feb 98